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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Computing Solutions



Comprehensive power management, switching, timing, and protection solutions for computing platforms from ON Semiconductor.



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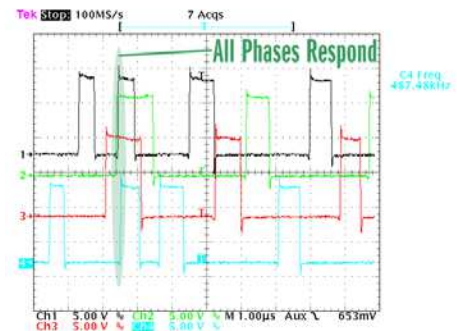
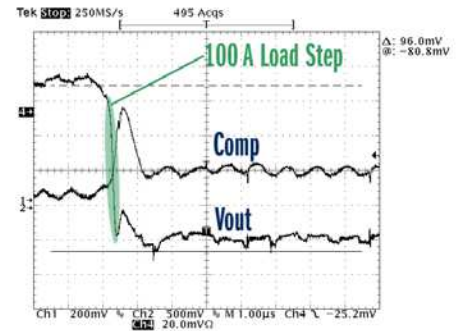
Dual-Edge & RPM Modulation Vcore Controllers for IMVP8 Designs

Features of Multi-Phase Dual Edge Architecture

- Current-mode dual-edge modulation for fast initial response to transient loading
- High-performance operational error amplifier
- Accurate total summing current amplifier
- High-impedance differential voltage and total current sense amplifiers
- Phase-to-phase dynamic current balancing
- “Lossless” DCR current sensing for current balancing

Features of Enhanced Single-Phase RPM Architectures

- High performance RPM control system
- Ultralow offset IO/UT monitor
- Dynamic VID feed-forward
- Programmable droop gain
- Zero droop capable
- Thermal monitor
- Ultra-sonic operation
- Digitally controlled operating frequency



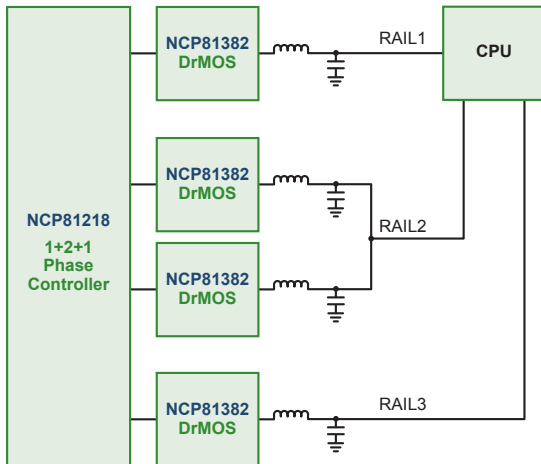
Device	Market	Function	VR Spec	Controller Architecture	Number of Rails	CPU Phases	Integrated Drivers	Interface	Package
NCP81201	Tablet	Controller	VR12.1	RPM	1	1	–	SVID	QFN-28
NCP81111	Microserver	Controller	VR12.5	Hybrid	1	1/2/3	–	SVID	QFN-32
NCP81203	Desktop	Controller	IMVP8	Dual Edge	2	3/2/1+2/1	–	SVID	QFN-52
NCP81203P	Notebook	Controller	IMVP8	Dual Edge	2	3/2/1+2/1	–	SVID	QFN-52
NCP81205	Notebook	Controller	IMVP8	Dual Edge & EN RPM	3	1/2/3+1/2/3+1	–	SVID	QFN-52
NCP81216	Ultrabook	Controller	IMVP8	Dual Edge & EN RPM	3	1+1/2+1	3 x 5 V	SVID	QFN-52
NCP81236	Ultrabook	Controller	IMVP8	Dual Edge & EN RPM	3	1/2+1+1	3 x 5 V	SVID	QFN-52
NCP81218	Ultrabook	Controller	IMVP8	Dual Edge & EN RPM	3	1+1/2+1	–	SVID	QFN-48
NCP81210	Ultrabook & Notebook	Controller	IMVP8	EN RPM	1	1	1 + FETs	SVID	QFN-40

Please contact ON Semiconductor for product datasheets.

Ultrabook Solution

NCP81218 1+2+1 Phase Controller

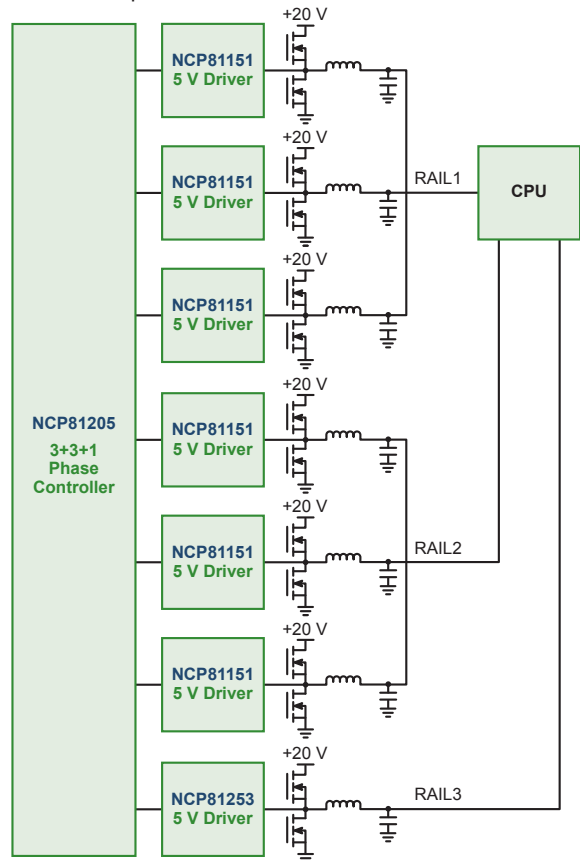
- Dual Edge & DCR current sensing for fast transient response
- EN RPM for fast transition between DCM and CCM mode
- True Differential Current Balancing
- IMVP8 compliant



Notebook Solutions

NCP81205 3+3+1 Phase Controller

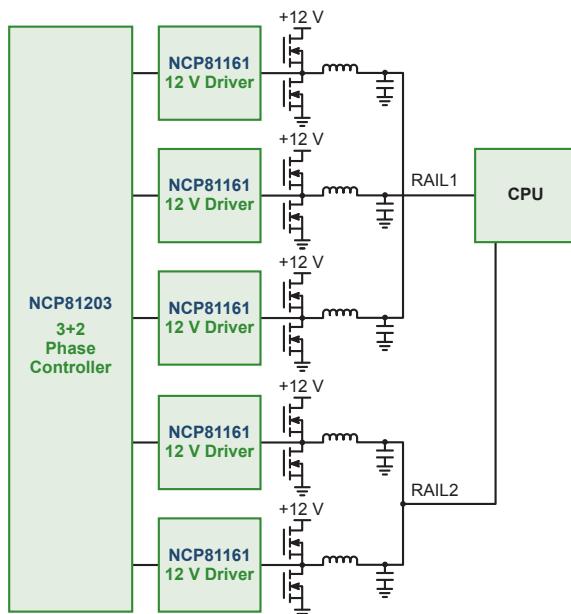
- Dual Edge & DCR current sensing for fast transient response
- EN RPM for fast transition between DCM and CCM mode
- True Differential Current Balancing
- IMVP8 compliant



Desktop Solutions

NCP81203 3+2 Phase Controller

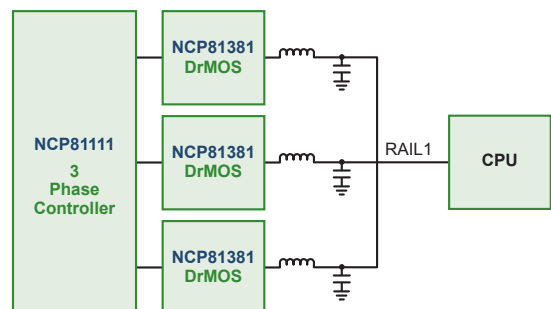
- Dual Edge for fast transient response
- Constant on-time for light load efficiency
- Supports all MLCC output capacitor solutions
- IMVP8 compliant



Microserver Solutions

NCP81111 3-Phase Digital Controller

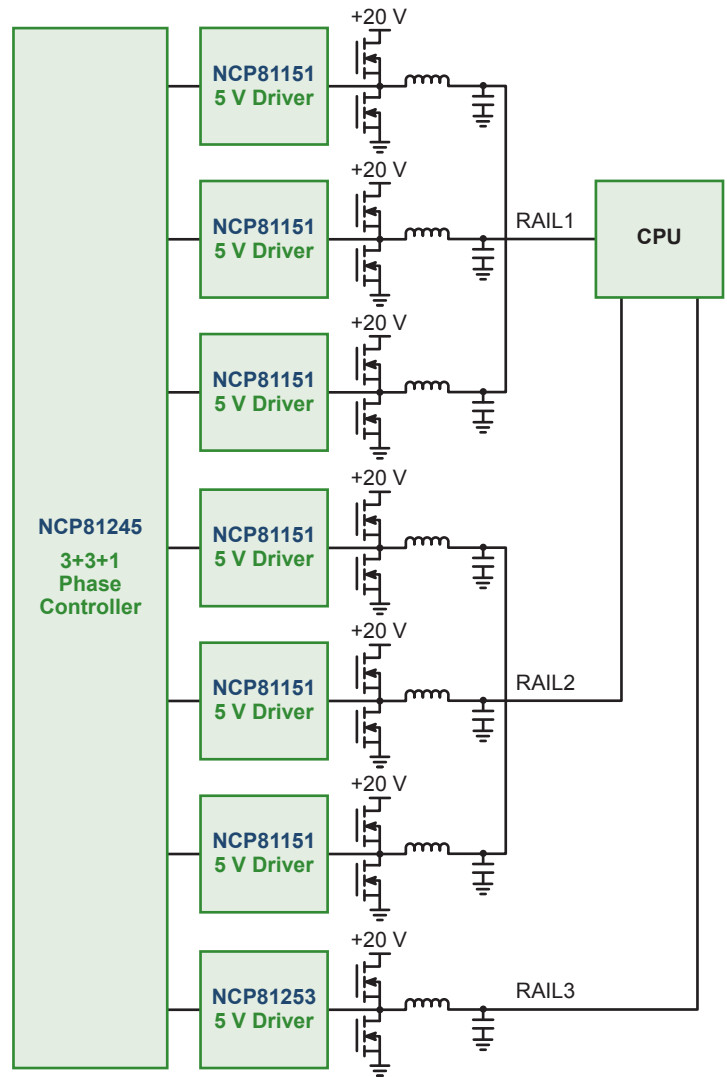
- Optimised to operate at 5MHz using DrMOS
- Can operate as general purpose I2C controller regulator
- Internal compensation using GUI interface
- VR12.5/6 compliant



IMVP8 Multiphase Controllers for Embedded Applications

NCP81245 3+3+1 Phase Controller

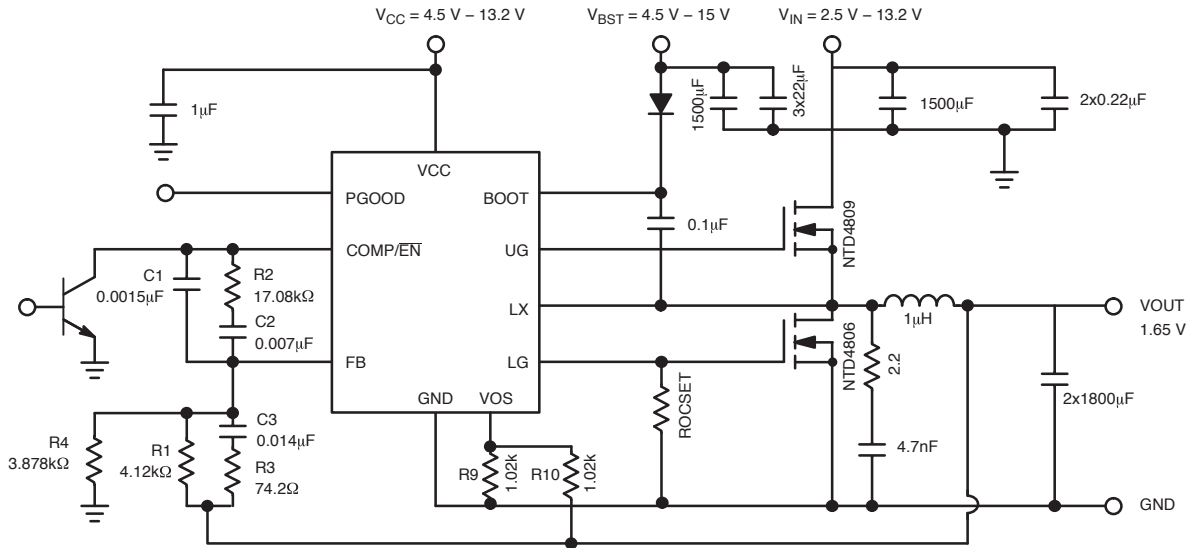
- Dual Edge & DCR current sensing for fast transient response
- EN RPM for fast transition between DCM and CCM mode
- True Differential Current Balancing
- IMVP8 compliant



Device	Market	Function	VR Spec	Controller Architecture	Number of Rails	CPU Phases	Integrated Drivers	Interface	Package
NCP81243	Desktop	Controller	IMVP8	Dual Edge	2	3/2/1+2/1	–	SVID	QFN-52
NCP81245	Notebook	Controller	IMVP8	Dual Edge & EN RPM	3	1/2/3+1/2/3+1	–	SVID	QFN-52
NCP81246	Ultrabook	Controller	IMVP8	Dual Edge & EN RPM	3	1+1/2+1	3 x 5 V	SVID	QFN-52
NCP81248	Ultrabook	Controller	IMVP8	Dual Edge & EN RPM	3	1+1/2+1	-	SVID	QFN-48
NCP81255	Ultrabook & Notebook	Controller	IMVP8	EN RPM	1	1	1 + FETs	SVID	QFN-40
NCP81145	Ultrabook & Notebook	5 V Driver	–	for Dual Edge Rail	–	–	–	–	DFN-8
NCP81146	Desktop	12 V Driver	–	for Dual Edge Rail	–	–	–	–	DFN-8
NCP81253	Ultrabook & Notebook	5 V Driver	–	for EN RPM rail	–	–	–	–	DFN-8

System Power

System power management devices provide additional rails in computing applications, beyond Vcore and graphics. They are available with single or dual channel operation, and also in multi-phase configurations.



NCP1589A Application Diagram

Device	Description	Topology	V _{CC} Min (V)	V _{CC} Max (V)	f _{sw} Typ (kHz)	Package
NCP1579	Synchronous Buck Controller, Low Voltage	Step-Down	4.5	13.2	275	SOIC-8
NCP1587	Synchronous Buck Controller, Low Voltage	Step-Down	4.5	13.2	250 - 300	SOIC-8
NCP1587A	Synchronous Buck Controller, Low Voltage	Step-Down	4.5	13.2	180 - 220	SOIC-8
NCP1589A	Synchronous Buck Controller, Low Voltage	Step-Down	4.5	13.2	—	DFN-10
NCP1589D	Synchronous Buck Controller	Step-Down	4.5	13.2	—	DFN-10
NCP1589L	Synchronous Buck Controller, Low Voltage, with Light Load Efficiency and Transient Enhancement	Step-Down	4.5	13.2	—	DFN-10
NCP5212	Single Synchronous Step Down Controller	Step-Down	4.5	27	300	QFN-16
NCP5217	Synchronous Buck Controller, Single	Step-Down	4.5	27	300	QFN-14
NCP5230	Low Voltage Synchronous Buck Controller	Step-Down	4.5	13.2	—	QFN-16
NCP5269	System Agent Controller with 2-bit VID	Step-Down	3.3	28	300 - 600	QFN-20
NCP3231	25 A Synchronous Buck Converter with Intergrated MOSFETs	Step-Down	4.5	18	500	TQFN-40
NCP3232N	15 A Synchronous Buck Converter with Intergrated MOSFETs	Step-Down	4.5	21	500	TQFN-40
NCP3133A	3 A Synchronous Buck Converter with Intergrated MOSFETs	Step-Down	2.9	5.5	1100	QFN-16
NCP3135	5 A Synchronous Buck Converter with Intergrated MOSFETs	Step-Down	2.9	5.5	1100	QFN-16

Thermal Management and System Monitoring

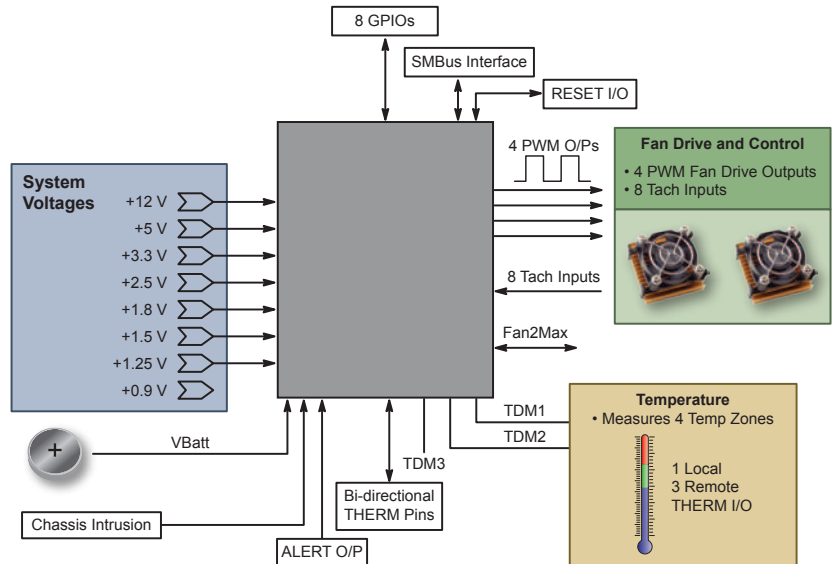
Extensive Portfolio

Local Sensors provide temperature information at the device location

Remote Sensors provide temperature information of a transistor located at a different position on the board; also includes local sensor capability

Fan Controllers integrate the temperature sensor with a fan controller/monitor

System Monitors integrate combinations of remote and/or local temperature sensing, voltage monitoring, fan control & monitoring, reset control, and GPIO functions

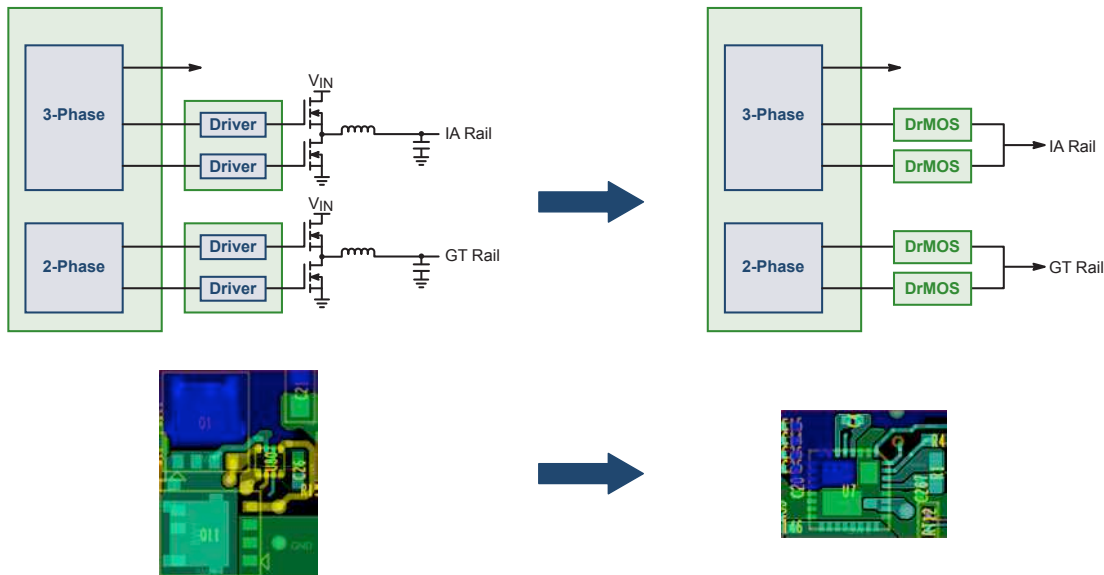


	Device	Supply Range (V)	Temperature Range (°C)	Local Accuracy (°C)	Interface	Number of Addresses	SRC (Ω)	Remote Accuracy	Remote Channels	Fan Channels	TACH Channels	Voltage Monitoring Channels	GPIOs	Package
System Monitors	ADM1026	3 - 5.5	-40 to +120	±3	I2C/SMBUS	3	—	±3	2	8	8	19	17	LQFP-48
	ADT7462	3 - 5.5	-40 to +125	±2.25	I2C/SMBUS	2	2 k	±2.25	3	4	8	13	8	LFCSOP-32
	NCT80	2.8 - 5.75	-40 to +125	±2	I2C/SMBUS	8	—	—	—	—	2	7	1	TSSOP-24
	ADT7476	3 - 3.6	-40 to +120	±1.5	I2C/SMBUS	3	—	±1.5	2	3	4	5	—	QSOP-24
Fan Controllers	ADT7473	3 - 3.6	-40 to +120	±1.5	I2C/SMBUS	3	3 k	±1.5	2	3	4			QSOP-16
	ADT7475	3 - 3.6	-40 to +120	±1.5	I2C/SMBUS	1	—	±1.5	2	3	4			QSOP-16
	ADM1033	3 - 3.6	-40 to +120	±1	I2C/SMBUS	8	1 k	±1	1	1	1			QSOP-16
	ADM1034	3 - 3.6	-40 to +120	±1	I2C/SMBUS	8	1 k	±1	2	2	2			QSOP-16
Remote Sensors	NCT72	2.8 - 3.6	-40 to +125	±1	I2C/SMBUS	2	1.5 k	±1	1					DFN-8, WDFN-8
	NCT218	1.4 - 2.75	-40 to +125	±1.75	I2C/SMBUS	2	150	±1	1					WDFN-8, WLCSOP-8
	NCT210	3 - 5.5	-55 to +125	±1	I2C/SMBUS	9	—	±3	2					QSOP-16
	ADM1032	3 - 5.5	-40 to +125	±3	I2C/SMBUS	2	—	±1	1					SOIC-8, MSOP-8
	ADT7461	3 - 5.5	-40 to +125	±3	I2C/SMBUS	2	3 k	±1	1					SOIC-8, MSOP-8
	ADT7481	3 - 3.6	-40 to +125	±1	I2C/SMBUS	2	—	±1	2					MSOP-10
	ADT7483	3 - 3.6	-40 to +125	±1	I2C/SMBUS	9	—	±1	2					QSOP-16
Local Sensors	NCT375	3 - 5.5	-55 to +125	±1	SMBUS	8								DFN-8, SOIC-8, Micro8
	NCT475	3 - 5.5	-55 to +125	±1	SMBUS	4								WLCSOP-6
	NCT203	1.4 - 2.75	-40 to +125	±1.75	I2C/SMBUS	1								DFN-8, SOIC-8, Micro8

Integrated MOSFET and Drivers

Features

- Integrated high- and low-side MOSFETs
- Integrated bootstrap diode
- Matched of driver and MOSFETs optimize switching performance
- Higher switching frequency enables use of smaller inductor and output capacitors
- Low-side MOSFET diode emulation mode provides asynchronous operation
- 65% lower BOM; 45% smaller footprint and simplified layout versus discrete solutions



Discrete

versus

Integrated

Device	PWM Input	V_{IN} Max (V)	Freq Max (MHz)	I_{OUT} Continuous Max (A)	Package
NCP5369	5 V Tri-state	25	1	40	QFN-40
NCP81081	3.3 V Tri-state	25	1	40	QFN-40
NCP5338	5 V Tri-state	20	1	40	QFN-40
NCP81380	5 V Tri-state	30	2	15	QFN-32
NCP81381	5 V Tri-state	30	2	25	QFN-32
NCP81382	5 V Tri-state	30	2	35	QFN-28

Drivers for Discrete MOSFET Implementations

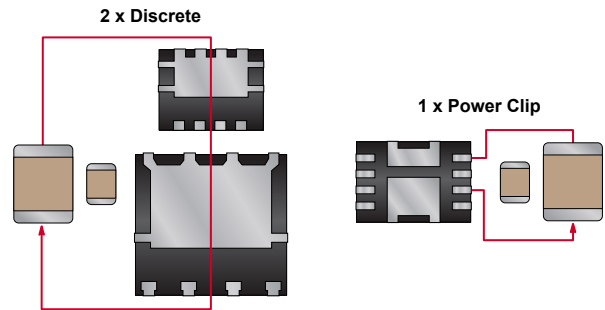
Drivers specifically designed to work with controller solutions, and optimized for 5 V or 12 V gate applications.

Device	Drivers	V_{CC} Typ (V)	Integrated Bootstrap Diode	Zero Crossover Detection	Package
NCP5901	Single	12	N	Y	DFN-8
NCP5901B	Single	12	Y	Y	DFN-8
NCP81161	Single	12	Y	Y	DFN-8
NCP81151	Single	5	Y	Y	DFN-8
NCP81253	Single	5	Y	N	DFN-8
NCP81061	Dual	12	Y	Y	QFN-16
NCP81152	Dual	5	Y	Y	QFN-16

High Performance Dual MOSFETs (Power Clip)

Features

- Co-packaged high-side & low-side MOSFETs reduces board space
- Optimized for low Figure-of-Merit = $R_{DS(ON)} \times Q_g$
- Improved clip for faster switching & improved efficiency
- Flipped low-side MOSFET improves thermal performance
- Parasitic inductance loops minimized for improved efficiency



High Frequency Switching Loop Size Reduction

Specific Applications

- GPU rails in VGA cards and gaming motherboards
- Vcore & system rails in notebooks

Device	Package	I _{max} (A)	BV _{DSS} (V)	V _{Gs} Max (V)	R _{DS(ON)} Max @ V _{Gs} = 4.5 V (mΩ)		Q _g Typ @ V _{Gs} = 4.5 V (nC)		C _{oss} Typ (pF)
					High Side	Low Side	High Side	Low Side	Low Side
FDPC8012S	Power Clip 33	15-20	25	12	7	2.2	8	25	885
FDPC8013S		10-15	30	20	9.6	2.7	6	21	997
FDMC2D2N025DSD*		15-20	25	16	7	2.2	5	15	886
FDMC2D3N03DSD*		15-20	30	16	7	2.4	5	15	1063
FDPC3D5N025X9D	Power Clip 35	10	25	12	3.7	3.7	17	17	612
FDPC8900*		14	30	12	5	6.5	12	8.8	356
FDPC8016S	Power Clip 56	20-30	25	12	4.7	1.7	11	31	1195
FDPC8014S		>30	25	12	4.7	1.4	11	43	1720
FDPC8014AS		>30	25	12	4.7	1.2	11	44	2170
FDMS001N025DSD*		>30	25	16	4	1.1	10	35	1810
FDMS1D2N03DSD*		>30	30	16	4	1.2	11	39	1845
FDPC5018SG		25	30	12	6.5	2	8	28	1210
FDPC5030SG	20	30	12	6.5	3	8	18	801	
NTMFD4H088NF*	Power Phase 56	25	30	12	11.3	2	3	21	1530
NTMFD4C85N*		>30	30	20	4.3	1.2	15	45	3660
NTMFD4C86N*		>30	30	20	8.1	3.4	11	22	1650

* Pending 1Q17.

Asymmetric Dual MOSFETs

Device	Package	I _{max} (A)	BV _{DSS} (V)	V _{GS} Max (V)	R _{DS(ON)} Max @ V _{GS} = 4.5 V (mΩ)		Q _g Typ @ V _{GS} = 4.5 V (nC)		C _{oss} Typ (pF)
					High Side	Low Side	High Side	Low Side	Low Side
FDMS3620S	Power 56 Dual	>30A	25	12	5.2mΩ	1.2mΩ	12	50	1828
FDMS3622S		25-30A			5.7mΩ	1.6mΩ	12	40	1405
FDMS3624S		20-25A			5.7mΩ	2.2mΩ	12	27	946
FDMS3626S		15-20A			5.7mΩ	3.2mΩ	12	19	716
NTMFD4901NF	S08-FL Dual	25-30A	30	20	10.0mΩ	3.5mΩ	10	20	1100
NTMFD4902NF		25-30A			10.0mΩ	6.2mΩ	10	12	813
NTMFD4C20N		25-30A			10.8mΩ	5.2mΩ	9	13	990
FDMC007N30D	Power 33 Dual	<13A	20	12	13.3mΩ	7.0mΩ	6.4	14	413
FDMC8200S		<6A			32.0mΩ	13.5mΩ	3.1	7.2	373

30 V P-Channel MOSFETs

Device	Package	Configuration	Breakdown V _{DS} /V _{GS} (V)	R _{DS(ON)} Max @ V _{GS} = 4.5 V (mΩ)
FDMC013P030Z	MLP 33	Single P-Channel	30/25	13.2
FDMC6675BZ		Single P-Channel	30/25	27
FDMC6679AZ		Single P-Channel	30/25	18
FDMA6676PZ	MLP 22	Single P-Channel	30/25	27
FDMA530PZ		Single P-Channel	30/25	65

Common Drain Dual N-Channel MOSFET

FDPC4044

- 30 V, 27 A
- Max r_{S1S2(on)} = 4.3 mΩ at V_{GS} = 10 V, I_{S1S2} = 27 A
- MLP 33 package

Specific Applications

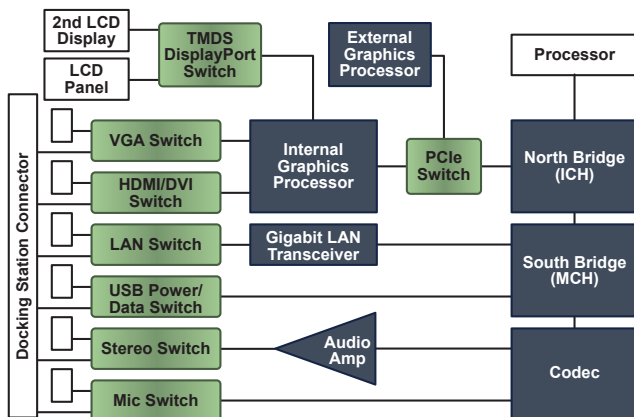
- V_{BUS} back-back protection switch for USB Type-C
- Replace two discrete back-back MOSFETs with single compact solution

N-Channel MOSFETs

Device	Package	Polarity	Maximum Ratings				Q _g (nC)	Q _{gd} (nC)	C _{iss} (pF)	C _{rss} (pF)	R _G (Ω)	Applications
			V _{DS} (V)	V _{GS} (V)	R _{DS(ON)} (mΩ)							
					V _{GS} =10 V	V _{GS} =4.5 V						
NTMFS4C020N	SO-8FL	N-Channel	30	20	0.7	1	63	13	10144	148	1	HPPC
NTMFS4C01N		N-Channel	30	20	0.9	1.2	65	18	9200	231	1	HPPC
NTMFS4C022N		N-Channel	30	20	1.7	2.4	20.8	4.7	3071	67	1	HPPC
NTMFS4C03N		N-Channel	30	20	2.3	3.3	19.8	5.3	2789	71	1	HPPC
NTMFS4C024N		N-Channel	30	20	2.8	4	14	5	1972	59	1	Synchronous Side
NTMFS4C35N		N-Channel	30	20	3.2	4.2	15	5.5	2300	46	1	Synchronous Side
NTMFS4C025N		N-Channel	30	20	3.4	4.9	11.6	4	1683	40	1	Synchronous Side
NTMFS4C05N		N-Channel	30	20	3.4	5	13	3	1950	50	1	Synchronous Side
NTMFS4C06N		N-Channel	30	20	4	6	14.5	5.5	1988	71	1	Synchronous Side
NTMFS4C028N		N-Channel	30	20	4.7	7	10.9	5.4	1252	126	1	Synchronous Side
NTMFS4C08N		N-Channel	30	20	5.8	8.5	8.7	2.8	1100	38	1	Synchronous Side
NTMFS4C09N		N-Channel	30	20	6	8.8	10.9	5.4	1252	126	1	Control Side
NTMFS4C029N		N-Channel	30	20	5.9	9	9.7	4.8	987	162	1	Control Side
NTMFS4C10N		N-Channel	30	20	7	10.8	9.3	4.2	970	125	1	Control Side
NTMFS4C032N		N-Channel	30	20	7.4	11.1	7.8	3.7	770	127	1	Control Side
NTMFS4C13N		N-Channel	30	20	9.1	13.8	6.6	2.7	720	95	1	Control Side
NTTFS4C02N*	μ8-FL	N-Channel	30	20	2	3	20	7	2800	66	0.8	HPPC
NTTFS4C05N		N-Channel	30	20	3.6	5.1	13	3	1950	50	1	Synchronous Side
NTTFS4C06N		N-Channel	30	20	4	6	14.5	5.5	1988	71	1	Synchronous Side
NTTFS4C08N		N-Channel	30	20	5.8	8.5	8.7	2.8	1100	38	1	Synchronous Side
NTTFS4C10N		N-Channel	30	20	7.4	11	9.3	4.2	970	125	1	Control Side
NTTFS4C13N		N-Channel	30	20	9.1	13.8	6.6	2.7	720	95	1	Control Side
NTTFS4C25N		N-Channel	30	20	17	26.5	4	1.3	455	60	1	Control Side

Switching Devices

ON Semiconductor offers a range of switching devices for high speed interface in servers, desktop computing, notebook and netbook computers. Applications include PCI Express, DisplayPort, Gigabit Ethernet and USB 2.0.



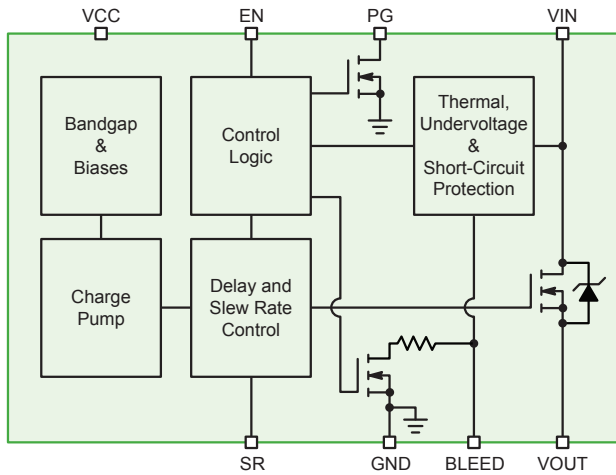
Server Implementation

Device	Interface	Data Rate	No Channels	Quiescent Current
NCN3612B	PCIe 3.0, DisplayPort 1.2	8 Gb/s	12	250 μA
NCN3411	PCIe 3.0	8 Gb/s	8	200 μA
NCN2612B	PCIe 2.0, DisplayPort 1.1	5 Gb/s	12	250 μA
NS3L500	Gigabit Ethernet	1 Gb/s	11	250 μA
NCN1188	USB 2.0 / MHL	2.25 Gb/s	2	21 μA
NS5S1153	USB 2.0	480 Mb/s	2	21 μA
NLAS7242	USB 2.0	480 Mb/s	2	1 μA
NLAS52231	Audio	36 MHz	2	1 μA
NLAS4684	Audio	9.5 MHz	2	180 nA

Advanced Load Switches

ON Semiconductor provides a comprehensive range of load switches, suitable for a variety of different power trees.

- Copackaged MOSFET plus CMOS controllers – value-added features plus high performance
- Monolithic CMOS smart load switches – value added features, low cost
- Discrete MOSFETs – simple, high performance



NCP45xxx Integrated Load Switch Feature

- Simple/clean design
- No current consumption in standby power mode
- Small PCB footprint
- Low RDS(ON) due to charge pump driving NMOS
- Adjustable soft-start time (SR)
- Adjustable integrated discharge
- Fault protection
- Power rail monitoring & sequencing

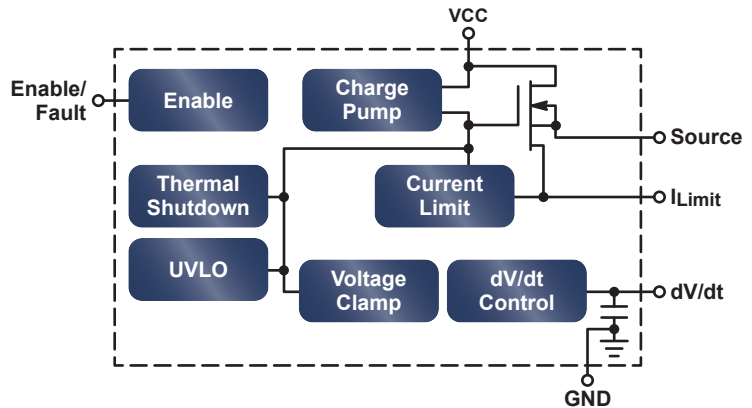
Type	Device	r _{on} (mΩ)	I Max (A)	V _I Min (V)	V _I Max (V)	I _q (μA)	Discharge	Slew Rate (μs)	Features	Package(s)
Smart Load Switch	NCP330	26 at 3.3 V	3	1.8	5.5	100	-	2000	Reverse blocking	TDFN-4
	NCP333	55 at 3.3 V	1.5	1.2	5.5	1	Auto	95	-	WLCSP-4
	NCP334	47 at 3.3 V	2	1.2	5.5	1	-	71	-	WLCSP-4
	NCP335	47 at 3.3 V	2	1.2	5.5	1	Auto	71	-	WLCSP-4
	NCP336	23 at 3.3 V	3	1.2	5.5	1	-	810	-	WLCSP-6
	NCP337	23 at 3.3 V	3	1.2	5.5	1	Auto	810	-	WLCSP-6
	NCP338	27 at 1.8 V	2	1	3.6	0.6	Auto	20	-	WLCSP-6
	NCP339	26 at 3.3 V	3	1.2	5.5	2	-	2700	Reverse blocking	WLCSP-6
	NCP432	50 at 1.8 V	1.5	1	3.6	0.6	-	20	-	WLCSP-4
	NCP433	50 at 1.8 V	1.5	1	3.6	0.6	Auto	20	-	WLCSP-4
	NCP434	43 at 1.8 V	2	1	3.6	0.6	-	61	-	WLCSP-4
	NCP435	43 at 1.8 V	2	1	3.6	0.6	Auto	61	-	WLCSP-4
	NCP436	23 at 1.8 V	3	1	3.6	1	-	27	-	WLCSP-6
	NCP437	23 at 1.8 V	3	1	3.6	1	Auto	27	-	WLCSP-6
ecoSWITCH™ Integrated Load Switch	NCP45524	18.0	6	0.5	13.5	-	Adj	-	Power good	DFN-8
	NCP45525	18.0	6	0.5	13.5	-	Adj	Adj	-	DFN-8
	NCP45560	2.4	24	0.5	13.5	-	Adj	Adj	Power good; Fault	DFN-12
	NCP45540	3.3	20	0.5	13.5	-	Adj	Adj	Power good; Fault	DFN-12
	NCP45541	3.3	20	0.5	13.5	-	Adj	Adj	Power good	DFN-12
	NCP45520	9.5	10.5	0.5	13.5	-	Adj	-	Power good; Fault	DFN-8
	NCP45521	9.5	10.5	0.5	13.5	-	Adj	Adj	Fault	DFN-8

Electronic Fuse for SATA, eSATA, USB

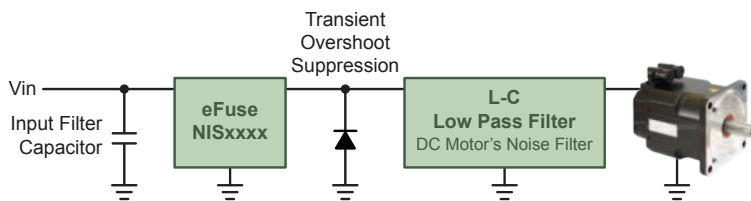
3 - 12 V Power Bus Hot Plug Protection

Features

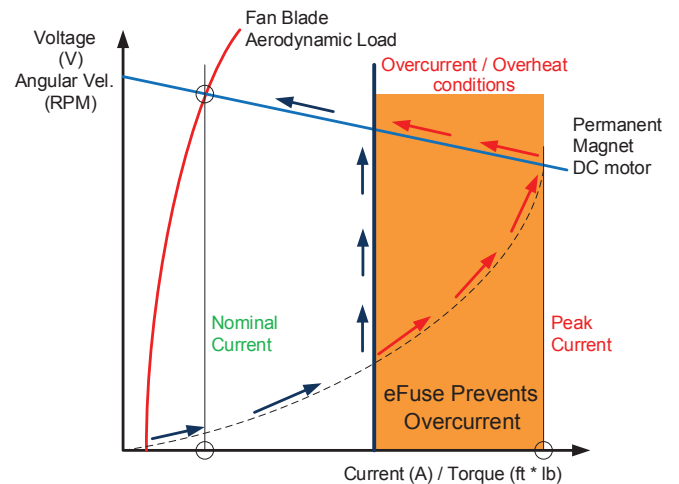
- Low $R_{DS(ON)}$, high operating and trip currents (IOP, ITRIP)
- Overvoltage protection
- Precise ITRIP control
- Slew rate control
- Thermal shut-down
- EN pin for synchronizing multiple eFuses
- Outperforms poly-fuses:
 - Tighter spec tolerances
 - Lower resistance
 - Shorter trip-time
 - Superior repeatability
- High efficiency with high current capability
- eFuses in parallel achieve practically any desired level of IOP and ITRIP



Typical Feature Set for eFuse



Typical Application Block Diagram



DC Motor I/V Characteristics

Device	Input Voltage (V)	Output Clamping Voltage (V)	ITRIP Trip Current (A)	R _{DS(ON)} (mΩ)	Adjustable ITRIP	Auto Recovery	Latching	Package
NIS5112	-0.6 to 18	15	2.5	28	Yes	Yes	Yes	SOIC-8
NIS5132	-0.6 to 18	15	3.5	44	Yes	Yes	Yes	DFN-10
NIS5232	-0.6 to 18	15	4	44	Yes	No	Yes	DFN-10
NIS5135	-0.6 to 18	6.65	3.5	68	Yes	Yes	Yes	DFN-10
NIS5452	-0.6 to 14	5.85	2.1	40	Yes	No	Yes	WDFN-10
NIS5431	-0.6 to 14	3.85	1.6	45	Yes	No	Yes	WDFN-10

Ethernet: 10/100BASE-T, 1000BASE-TX, and Gigabit

Four Pairs, Low Capacitance Surge and ESD Protection

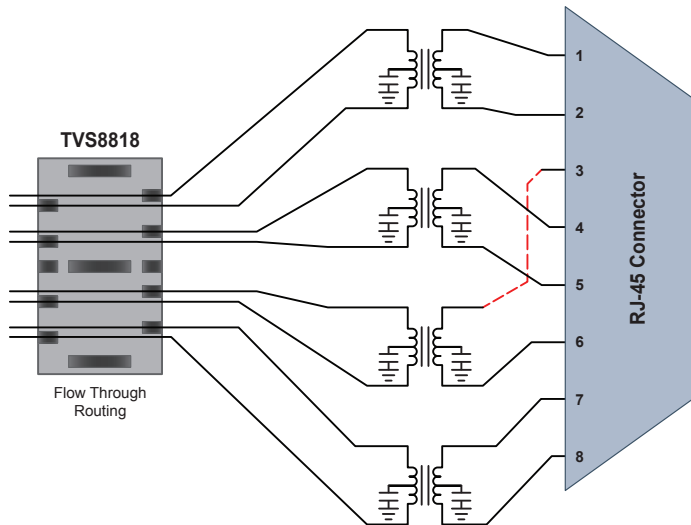
The 1000BASE-T or Gigabit Ethernet interface operating at higher bitrates is susceptible to ESD strikes, cable-discharge events and lightning-induced transients. Our products help meet IEC 61000-4-5, GR-1089-CORE and other Standards.

Features

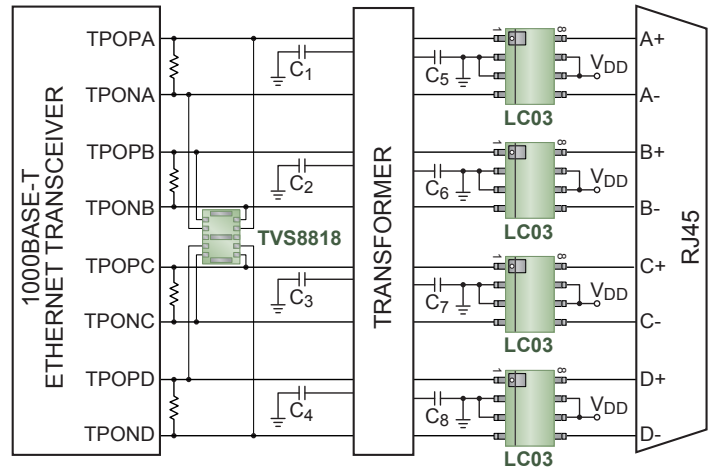
- Line-to-line capacitance < 3 pF
- V_{clamp} (25 A surge) < 11 V
- IEC 61000-4-2 rating > 30 kV
- No latching danger
- Surge rating maintained to 125°C

Benefits

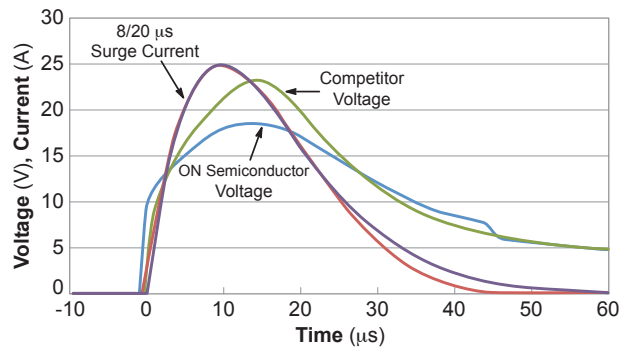
- Compatible with Gb Ethernet and beyond
- Enhanced protection for downstream electronics
- Accommodates operating transients above 3.3 V
- Small form-factor allows integration into connectors



Typical Application



Line Side : LC03-6 (optional)
Transformer Side: TVS8818
Protection against metallic (transverse) strikes



Line-to-Line Surge

Surge Protection Devices

Device	V_{DC} Max (V)	Line Transient Max (V)	Surge I_{PP} , 8/20 μ s (A)	Typical Line-Line Capacitance (pF)	ESD Contact Rating (kV)	Package
LC03-6	6.7	7.0	100	8.0	\pm 30	SOIC-8
TVS4201	5.0	6.0	25	1.5	\pm 30	TSOP-6
TVS8814	3.0	3.2	35	1.5	\pm 30	UDFN-8
TVS8818	3.0	3.2	35	1.5	\pm 30	UDFN-10
NUP4114H	5.0	5.0	12*	0.4	\pm 13	TSOP-6
SRDA3.3	3.3	5.0	25	4.0	\pm 8	SOIC-8
SRDA05	5.0	7.0	23	5.0	\pm 8	SOIC-8

* On Pin 5.

USB 3.x Type A Connector

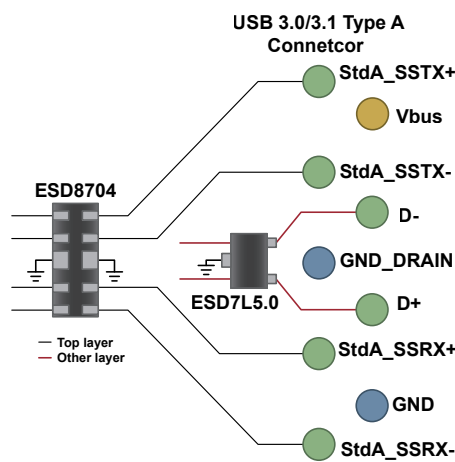
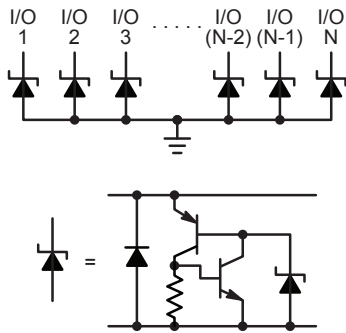
Two SuperSpeed Pairs, One High Speed Pair, V_{CC}, Low Capacitance ESD Protection

Key Requirement

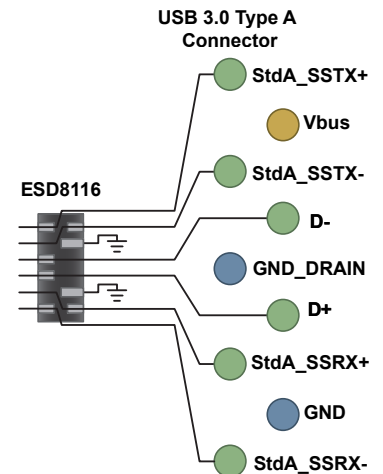
- Cap < 0.7 pF

Features

- 0.35 pF
- Flow through routing
- Industry leading low clamping voltage versus competitors

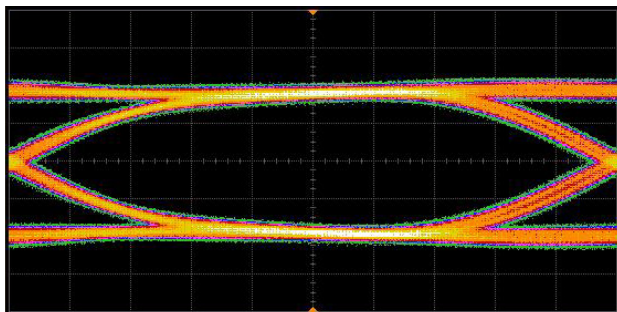


ESD8704 – 0.35 pF, 2 Layer Routing
(ESD8704; ESD7L5.0 for D+, D- Lines)

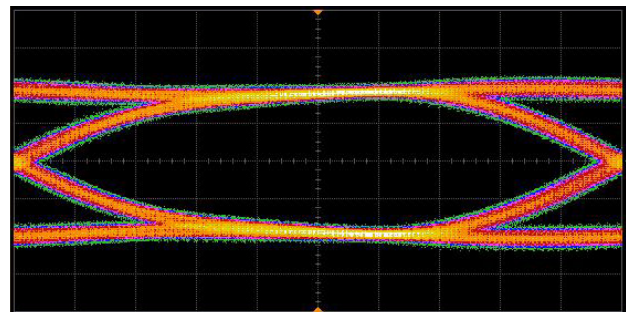


ESD8116 – 0.30 pF, 1 Layer Routing

Device	Interface	Data Lines	Capacitance (pF)	Package	Size (mm)
ESD8704	USB 3.x	2 Pair (Tx, Rx)	0.35	UDFN-10	2.5 x 1.0
ESD7L	USB 3.x	1 Pair (D+/-)	0.5	SOT-723	1.2 x 1.2
ESD8504	USB 3.0	2 Pair (Tx, Rx)	0.4	UDFN-10	2.5 x 1.0
ESD8104	USB 3.0	2 Pair (Tx, Rx)	0.3	UDFN-10	2.5 x 1.0
ESD8116	USB 3.0	3 Pair (Tx, Rx, D+/-)	0.3	UDFN-8	2.0 x 1.2
ESD8011	USB 3.x	Single Line	0.10	X3DFN-2	0.62 x 0.32
ESD8101	USB 3.x	Single Line	0.20	DSN-2	0.43 x 0.23
ESD8111	USB 3.x	Single Line	0.20	WLCSP-2	0.6 x 0.3
ESD8006	USB 3.0	3 Pair (Tx, Rx, D+/-)	0.25	UDFN-8	3.3 x 1.0



Without ESD



With ESD

USB 3.0 @ 5 Gb/s

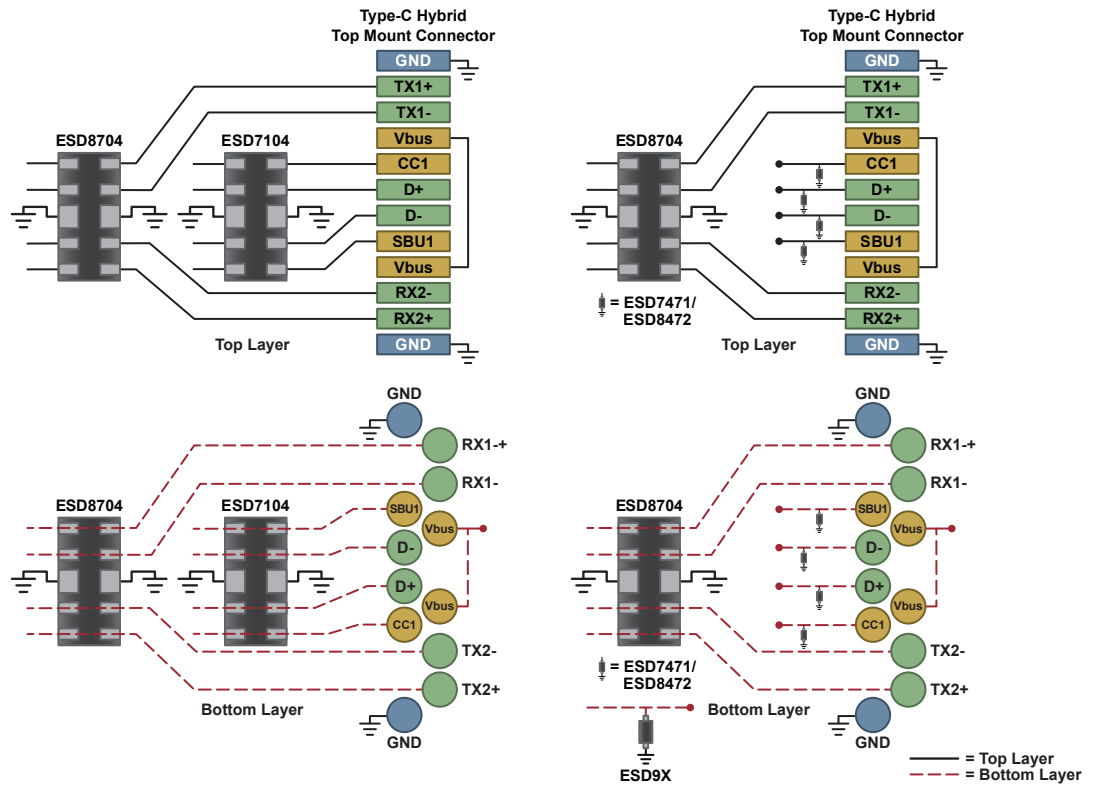
USB 3.x Type C Connector

Key Requirement

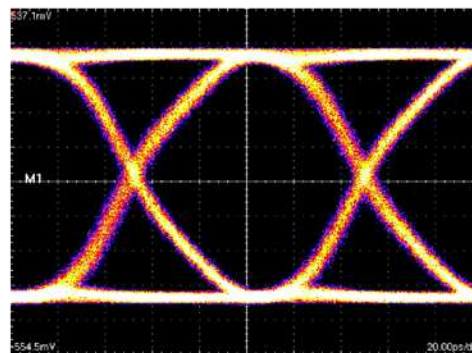
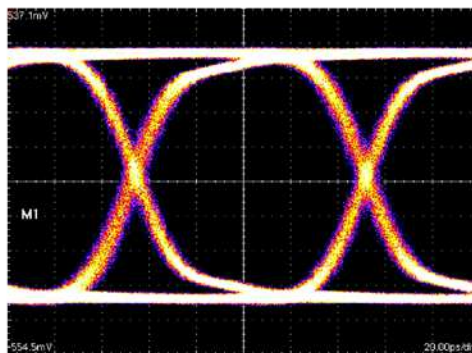
- Cap < 0.5 pF

Features

- 0.35 pF
- Flow through routing
- Industry leading low clamping voltage versus competitors



Device	Data Lines	Capacitance (pF)	Package	Size (mm)
ESD8704	2 Pair (Tx, Rx)	0.37	UDFN-10	2.5 x 1.0
ESD7104	2 Pair (CC, SBU, D+/-)	0.30	UDFN-10	2.5 x 1.0
ESD8011	Single Line (Tx, Rx)	0.10	X3DFN-2	0.62 x 0.32
ESD8101	Single Line (Tx, Rx)	0.20	DSN-2	0.43 x 0.23
ESD8111	Single Line (Tx, Rx)	0.20	WLCSF-2	0.6 x 0.3
ESD8472	Single Line (CC, SBU, D+/-)	0.20	X3DFN-2	0.62 x 0.32
ESD7471	Single Line (CC, SBU, D+/-)	0.24	XDFN-2 (SOD-882)	1.0 x 0.6



Without ESD

With ESD

USB3.1 Eye Diagram with and without ESD8704. 10 Gb/s

USB 2.0

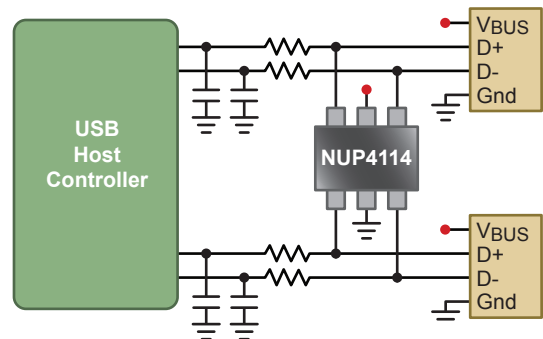
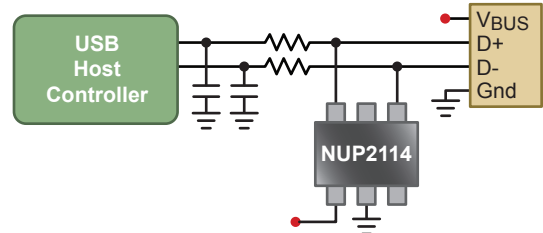
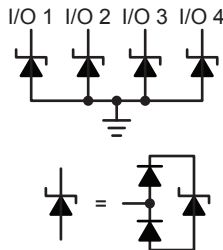
One High Speed Pair, V_{CC}, Low Capacitance ESD Protection

Key Requirement

- Cap < 5 pF

Features

- 0.35 - 3.0 pF
- Multi-part solutions available
- Industry leading low clamping voltage



Device	Data Lines	Capacitance (pF)	Package	Size (mm)
NUP2114UPX	1 Pair (D+/-) + Vbus	0.8	SOT-553	1.2 x 1.6
NUP2114UCM	1 Pair (D+/-) + Vbus	0.8	TSOP-6	3.0 x 2.75
NUP4114UPX	2 Pair (D+/-) + Vbus	0.5	SOT-563	1.6 x 1.6
NUP4114UCL	2 Pair (D+/-) + Vbus	0.5	SC-88	2.0 x 2.1
NUP4114H	2 Pair (D+/-) + Vbus	0.5	TSOP-6	3.0 x 2.75
TVS4201MR6	2 Pair (D+/-) + Vbus	3	TSOP-6	3.0 x 2.75
ESD7L5.0	2	0.5	SOT-723	1.2 x 1.2
ESD8351MUT	1	0.37	X3DFN-2	0.6 x 0.3
ESD8351P2T	1	0.37	SOD-923	1.0 x 0.6
ESD9L5.0	1	0.5	SOD-923	1.0 x 0.6

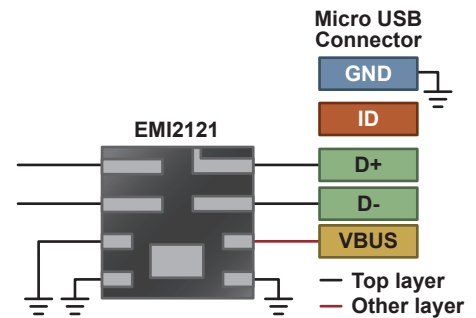
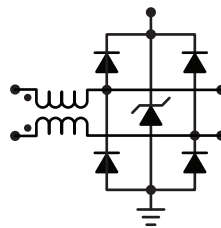
One High Speed Pair, V_{CC}, Common Mode Filter + ESD Protection

Key Requirement

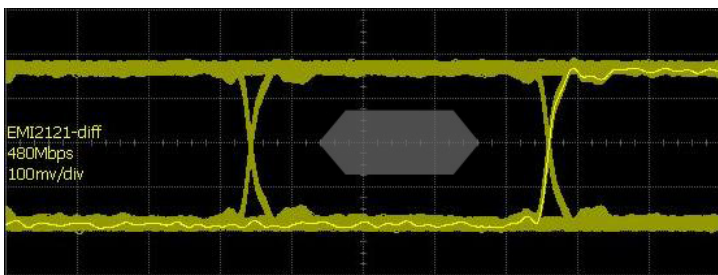
- Cap < 5 pF
- Common Mode Filtering

Features

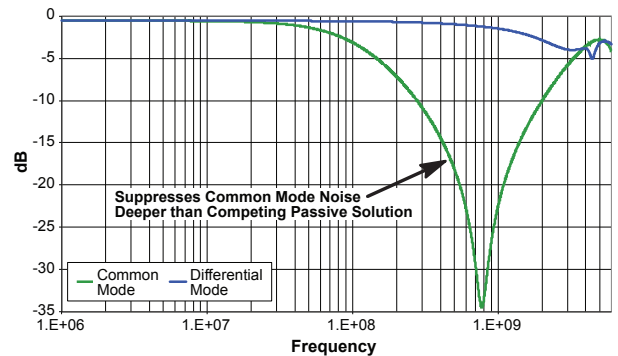
- 0.5 - 0.8 pF
- Integrated EMI suppression with ESD protection
- Industry leading low clamping voltage



Device	Pairs	Capacitance @ 2.5 V (pF)	CM Attenuation @ 800 MHz (-dB)	DM Bandwidth F3dB (GHz)	Package	Size (mm)
EMI2121	1	0.9	-25	2.5	WQFN	2.2 x 2.0 x 0.75



USB 2.0 @ 480 Mb/s



Thunderbolt

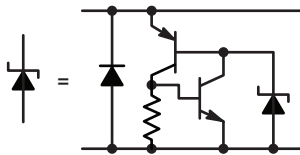
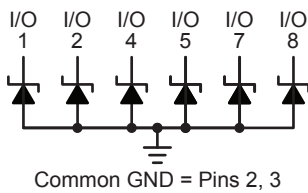
Four High Speed Pairs, up to Six Additional Lines, Low Capacitance ESD

Key Requirement

- Capacitance < 0.4 pF

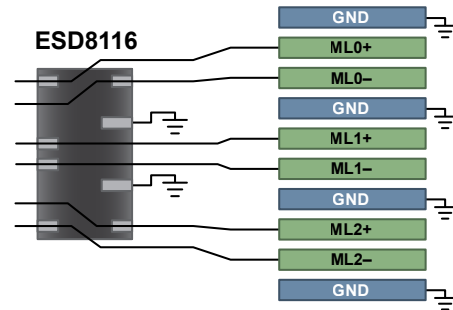
Features

- Capacitance of 0.35 pF or lower
- Integrated solution in 2.0 x 1.2 mm package
- Grounds between pairs to reduce cross-talk
- Flow-through routing
- Industry leading clamping voltage

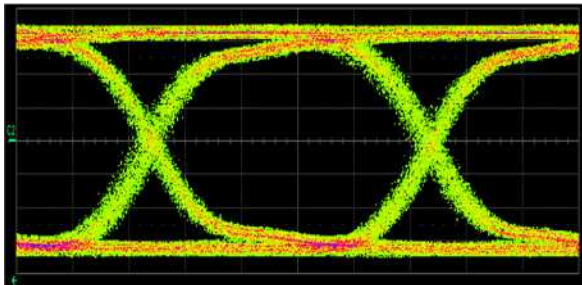
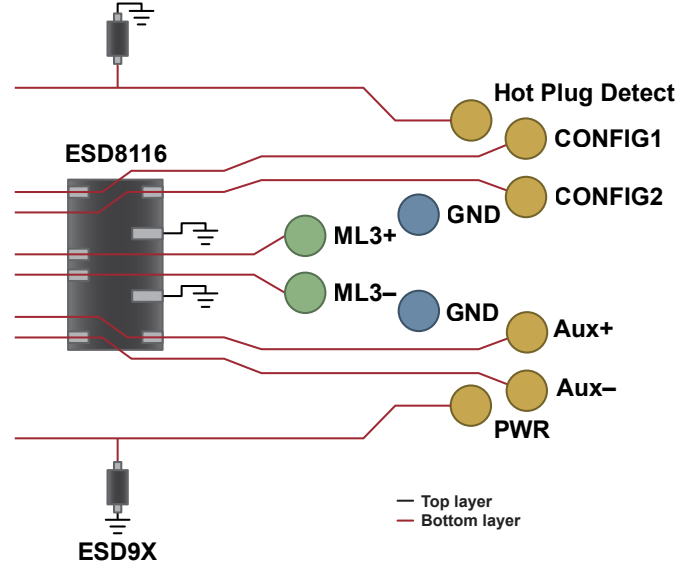


Device	Data Lines	Capacitance (pF)	Package	Size (mm)
ESD8006	3 Pair	0.25	UDFN-8	3.3 x 1.0
ESD8116	3 Pair	0.30	UDFN-8	2.0 x 1.2
ESD8011	Single Line	0.10	X3DFN-2	0.62 x 0.32
ESD8101	Single Line	0.20	DSN-2	0.43 x 0.23

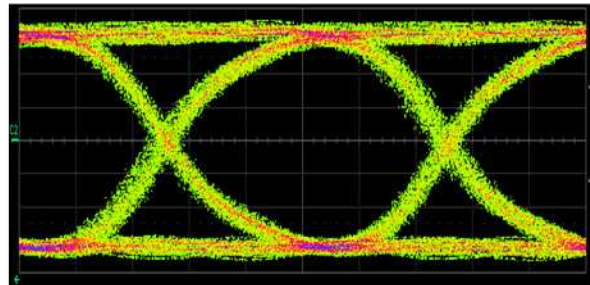
Thunderbolt Connector Top Layer



Thunderbolt Connector Bottom Layer



Without ESD8116



With ESD8116

Thunderbolt @ 10 Gb/s

HDMI, Display Port

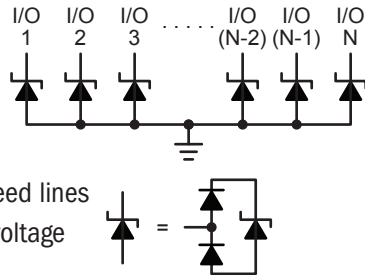
Four High Speed Pairs, Up to Six Additional Interface Lines, Low Capacitance ESD

Key Requirement

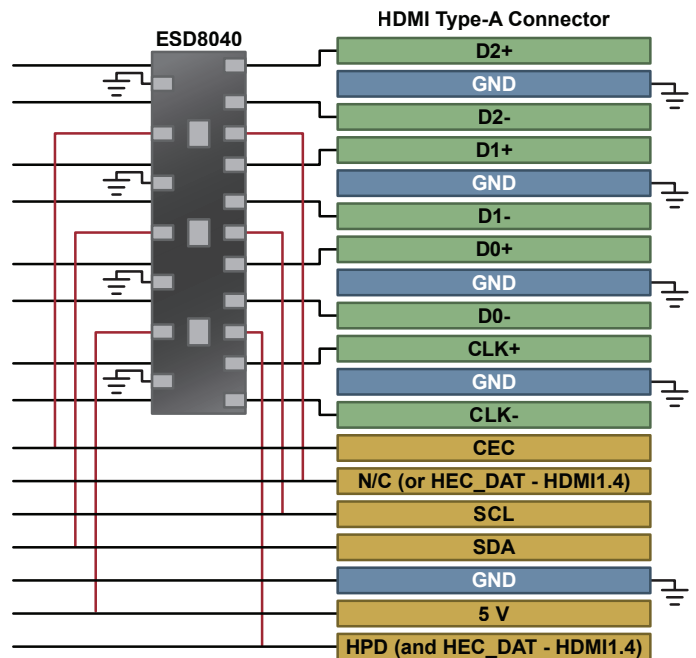
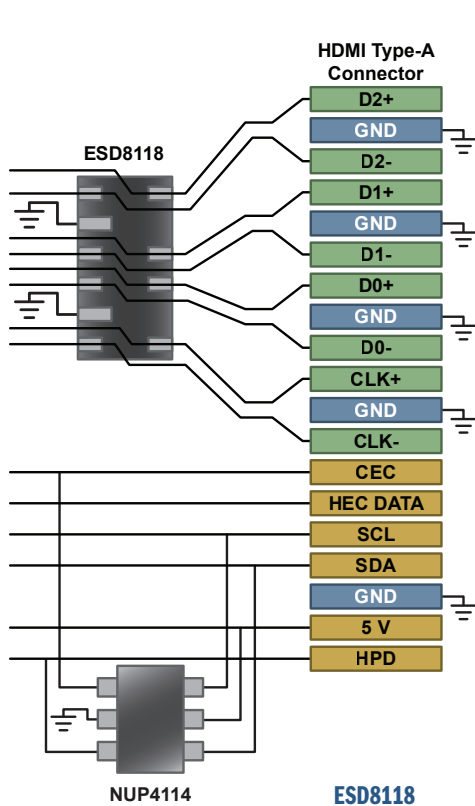
- Cap < 0.5 pF

Features

- 0.3 pF ESD protection
- Flow through routing in high speed lines
- Industry leading low clamping voltage

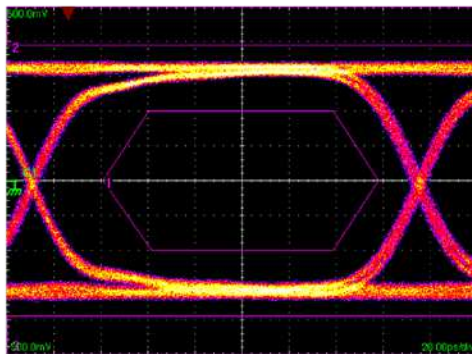


Device	Data Lines	Capacitance (pF)	Package	Size (mm)
ESD8104	4 (TMDS)	0.3	UDFN-10	2.5 x 1.0
ESD8118	8 (TMDS)	0.3	UDFN-10	3.2 x 1.2
ESD8040	14 (TMDS + Low Speed + Power)	0.3	UDFN-18	5.5 x 1.5
NUP4114UPX	5 (4 Low Speed + Power)	0.5	SOT-563	1.6 x 1.6
NUP4114UCL	5 (4 Low Speed + Power)	0.5	SC-88	2.0 x 2.1
NUP4114H	5 (4 Low Speed + Power)	0.5	TSOP-6	3.0 x 2.75

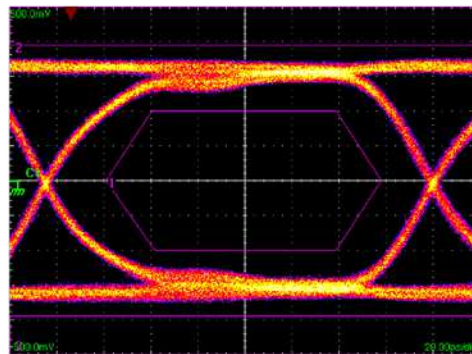


- MediaGuard fully integrated solution
- Includes ethernet protection (HDMI1.4)
- Backdrive current protection

— Top layer
— Other layer



Without ESD



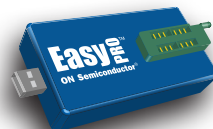
With ESD

HDMI 2.0 Eye Diagram with and without ESD8104. 6 Gb/s

EEPROMs for Configuration and Calibration

Features

- Broad density range: 1 kb to 2 Mb
- Wide operating Vcc range: 1.8/1.7 V to 5.5 V
- High endurance: 1 million program/erase cycles
- Wide temperature range: industrial and extended



EasyPRO™ is a user-friendly, portable programming tool for ON Semiconductor serial EEPROMs (I²C, SPI, Microwire)

EEPROMs

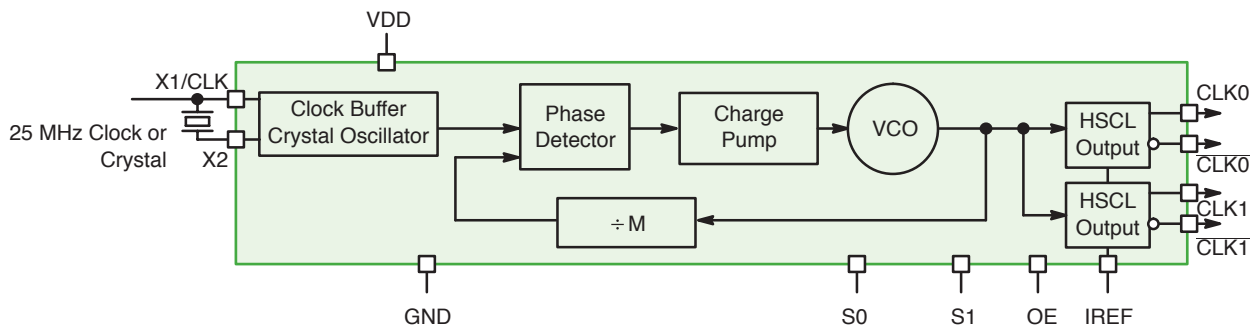
Data Transmission Standard	Device	Density	Organization*	Vcc Min (V)	Vcc Max (V)	fCLK Max (MHz)	Package(s)
I ² C	CAT24M01	1 Mb	128k x 8	1.8	5.5	1	SOIC-8, TSSOP-8, UDFN-8
	CAT24C512	512 kb	64k x 8	1.8	5.5	1	SOIC-8, TSSOP-8, UDFN-8
	CAT24C256	256 kb	32k x 8	1.8	5.5	1	SOIC-8, TSSOP-8, UDFN-8
	CAT24C128	128 kb	16k x 8	1.8	5.5	1	SOIC-8, TSSOP-8, UDFN-8
	CAT24C64	64 kb	8k x 8	1.7	5.5	1	SOIC-8, TSSOP-8, UDFN-8
	N24C64	64 kb	8k x 8	1.7	5.5	1	US-8
	LE2464	64 kb	8k x 8	1.7	3.6	1	WLCSP-6
	CAT24C32	32 kb	4k x 8	1.7	5.5	1	SOIC-8, TSSOP-8, UDFN-8; WLCSP-5
	N24C32	32 kb	4k x 8	1.7	5.5	1	US-8
	LE2432	32 kb	4k x 8	1.7	3.6	1	WLCSP-6
	CAT24C16	16 kb	2k x 8	1.7	5.5	0.4	SOIC-8, TSSOP-8, UDFN-8, TSOT23-5, WLCSP-4, WLCSP-5
	LE2416	16 kb	2k x 8	1.7	3.6	1	WLCSP-6
	N24C16	16 kb	2k x 8	1.7	5.5	0.4	US-8
	CAT24C08	8 kb	1k x 8	1.7	5.5	0.4	SOIC-8, TSSOP-8, UDFN-8, TSOT23-5, WLCSP-4, WLCSP-5
	N24C08	8 kb	1k x 8	1.7	5.5	0.4	US-8
	CAT24C04	4 kb	512 x 8	1.7	5.5	0.4	SOIC-8, TSSOP-8, UDFN-8, TSOT23-5, WLCSP-4, WLCSP-5
	N24C04	4 kb	512 x 8	1.7	5.5	0.4	US-8
CAT24C02	2 kb	256 x 8	1.7	5.5	0.4	SOIC-8, TSSOP-8, UDFN-8, TSOT23-5, WLCSP-4, WLCSP-5	
N24C02	2 kb	256 x 8	1.7	5.5	0.4	US-8	
SPI	CAT25M02	2 Mb	256k x 8	1.7	5.5	10	SOIC-8
	CAT25M01	1 Mb	128k x 8	1.8	5.5	10	SOIC-8, TSSOP-8
	CAT25512	512 kb	64k x 8	1.8	5.5	20	SOIC-8, TSSOP-8, UDFN-8
	CAT25256	256 kb	32k x 8	1.8	5.5	20	SOIC-8, TSSOP-8, UDFN-8
	CAT25128	128 kb	16k x 8	1.8	5.5	20	SOIC-8, TSSOP-8, UDFN-8
	CAT25640	64 kb	8k x 8	1.8	5.5	20	SOIC-8, TSSOP-8, UDFN-8
	CAT25320	32 kb	4k x 8	1.8	5.5	20	SOIC-8, TSSOP-8, UDFN-8
	CAT25160	16 kb	2k x 8	1.8	5.5	20	SOIC-8, TSSOP-8, UDFN-8
	CAT25080	8 kb	1k x 8	1.8	5.5	20	SOIC-8, TSSOP-8, UDFN-8
	CAT25040	4 kb	512 x 8	1.8	5.5	20	SOIC-8, TSSOP-8, UDFN-8
	CAT25020	2 kb	256 x 8	1.8	5.5	20	SOIC-8, TSSOP-8, UDFN-8
CAT25010	1 kb	128 x 8	1.8	5.5	20	SOIC-8, TSSOP-8, UDFN-8	
Microwire	CAT93C86	16 kb	2k x 8 / 1k x 16	1.8	5.5	3	SOIC-8
	CAT93C86B	16 kb	2k x 8 / 1k x 16	1.8 / 1.65	5.5	4	SOIC-8, TSSOP-8, UDFN-8
	CAT93C76	8 kb	1k x 8 / 512 x 16	1.8	5.5	3	SOIC-8, TSSOP-8
	CAT93C76B	8 kb	1k x 8 / 512 x 16	1.8 / 1.65	5.5	4	SOIC-8, TSSOP-8, UDFN-8
	CAT93C66	4 kb	512 x 8 / 256 x 16	1.8	5.5	2	SOIC-8, TSSOP-8
	CAT93C56	2 kb	256 x 8 / 128 x 16	1.8	5.5	2	SOIC-8, TSSOP-8
	CAT93C46	1 kb	128 x 8 / 64 x 16	1.8	5.5	2	SOIC-8, TSSOP-8
CAT93C46B	1 kb	128 x 8 / 64 x 16	1.8 / 1.65	5.5	4	SOIC-8, TSSOP-8, UDFN-8	

* Organization for Microwire devices is selectable.

Clock Synthesizers for High Performance Computing

Features

- Uses 25 MHz fundamental mode parallel resonant crystal
- PCI-e Gen 1, 2, 3, and 4 jitter compliant HCSL differential outputs
- NB3N50134 features configurable spread spectrum outputs
- NB3N51044 features individual OE control signal for each output, PLL bypass mode and an Input multiplexer
- NB3N51054 features I2C interface for OE control and configurable spread spectrum outputs
- 3.3 V supply



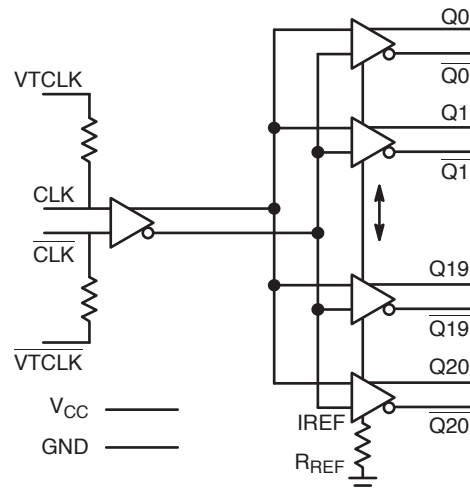
NB3N5573 Simplified Logic Diagram

Device	Number of Inputs	Input Type	f_{in} Typ (MHz)	Number of Outputs	Output Type	f_{out} Typ (MHz)	Spread Spectrum Outputs	Package
NB3N3002	1	Crystal; LVCMOS; LVTTTL	25	1	HCSL	25; 100; 125; 200	No	TSSOP-16
NB3N5573	1	Crystal; LVCMOS; LVTTTL	25	2	HCSL	25; 100; 125; 200	No	TSSOP-16
NB3N51032	1	Crystal; LVCMOS; LVTTTL	25	2	HCSL	25; 100; 125; 200	Yes	TSSOP-16
NB3N51034	1	Crystal; LVCMOS; LVTTTL	25	4	HCSL	100: 200	Yes	TSSOP-20
NB3N51044	2	Crystal; LVCMOS; LVTTTL	25	4	HCSL	100: 125	No	TSSOP-28
NB3N51054	1	Crystal; LVCMOS; LVTTTL	25	4	HCSL	100	Yes	TSSOP-24

Fanout Buffers for High Performance Computing

Features

- DC up to 400 MHz
- Accepts LVPECL, LVDS, HCSL, and single-ended inputs
- Typical input clock frequencies: 100, 133, 156.25, 166, 322.26, or 400 MHz
- Typical propagation delay: 800 ps
- HCSL differential outputs
- Integrated 50 Ω input termination resistors
- IREF pin enables setting of output drive
- Additive phase jitter 0.1 ps typical @ 100 MHz; PCI-e Gen 3 jitter compliant
- Additive phase jitter 80 fs maximum @ 156.25 MHz with NB3L208K, NB3L204K, NB3L202K; DB800H, DB400H, DB200H compliant



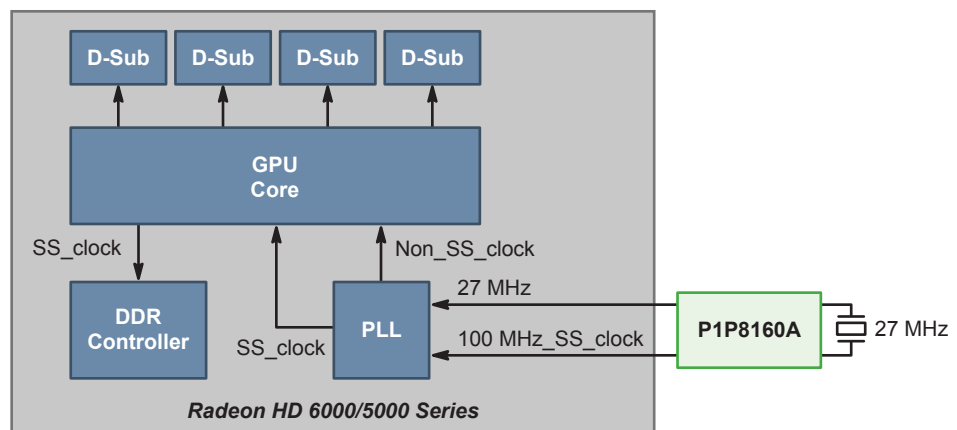
NB3N121K Logic Diagram

Device	Ratio	Additive Jitter(RMS) Typ (ps)	t _{skew(o-o)} Max (ps)	t _{pd} Typ (ns)	t _r & t _f Max (ps)	f _{maxClock} Typ (MHz)	Package
NB3L202K	1:2	0.046	30	1	125	350	QFN-16
NB3L204K	1:4	0.046	30	1	125	350	QFN-24
NB3N106K	1:6	0.1	100	0.8	400	400	QFN-24
NB3L208K	1:8	0.046	30	1	125	350	QFN-32
NB3N108K	1:8	0.1	100	0.8	400	400	QFN-32
NB3N111K	1:10	0.1	100	0.8	400	400	QFN-32
NB4N111K	1:10	<1	100	0.8	700	400	QFN-32
NB3N121K	1:21	0.1	100	0.8	700	400	QFN-52
NB4N121K	1:21	<1	50	0.8	700	200	QFN-52
NB3M8T3910G	3:1:10	0.05	50	1	300	1400	QFN-48

Computing Clock for Graphics

P1P8160A Features

- Provides reference clock to the GPU & reduces EMI in the GDDR interface
- Input frequency 27 MHz; crystal or reference clock
- Output frequency 100 MHz spread spectrum clock; 27 MHz RefOUT
- Two tri-level logic pins for selecting eight frequency deviations along with SSOFF
- Modulation rate at 100 MHz: 32 kHz
- Low cycle-cycle & long term jitter
- Supply voltage: 3.3 V \pm 10%
- WDFN-10 package

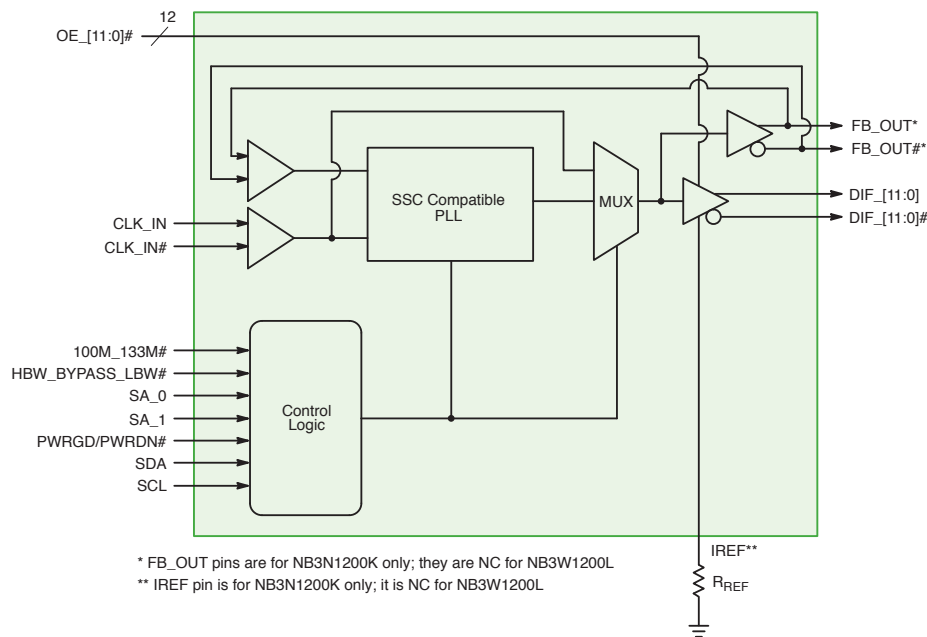


P1P8160A for AMD Graphics Card Application

Zero Delay Buffers Compliant with DB Specifications

Features

- Differential SRC clock support
- NB3N1900K, NB3N1200K: DB1900Z and DB1200Z compliant with 19 and 12 HCSL output pairs respectively
- NB3W1900L, NB3W1200L, NB3W800L: DB1900ZL, DB1200ZL, and DB800ZL compliant with 19, 12, and 8 low power NMOS push-pull output pairs respectively
- Optimized for 100 MHz and 133 MHz to meet PCIe Gen 2, Gen 3, Gen 4, and Intel QPI and UPI phase jitter specifications
- Spread spectrum compatible for low EMI
- Pseudo-external fixed-feedback for low input-to-output delay variation
- Individual OE control pin for each output
- SMBUS programmability for power down mode, PLL BW modes, PLL/Bypass mode & frequency selection



NB3N1200K Simplified Block Diagram

Device	Ratio	Output	t _{jitter(Cy-Cy)} Typ (ps)	t _{skew(I-o)} Max (ps)	t _{skew(o-o)} Max (ps)	Edge Rate Max (V/ns)	Package
NB3W800L	1:8	Low power NMOS push-pull	34	±100	50	4	QFN-48
NB3N1200K	1:12	HCSL	50	±100	50	4	QFN-64
NB3W1200L	1:12	Low power NMOS push-pull	50	±100	50	4	QFN-64
NB3N1900K	1:19	HCSL	50	±100	65	4	QFN-72
NB3W1900L	1:19	Low power NMOS push-pull	50	±100	85	4	QFN-72

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